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## FAIRCHILD



## Features

- $\operatorname{Max} \mathrm{r}_{\mathrm{DS}(o n)}=1.5 \Omega$ at $\mathrm{V}_{\mathrm{GS}}=-10 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=-1.5 \mathrm{~A}$
- Low Crss ( typical 10pF)
- Fast Switching
- Low gate charge ( typical 6.2 nC )

■ Improved dv / dt capability

- RoHS Compliant


## General Description

These P-Channel MOSFET enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as audio amplifier, high efficiency switching DC/DC converters, and DC motor control.

## Application

- Active Clamp Switch


MLP 3.3x3.3

MOSFET Maximum Ratings $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ unless otherwise noted

| Symbol | Parameter | Ratings | Units |
| :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\text {DS }}$ | Drain to Source Voltage | -150 | V |
| $\mathrm{V}_{\mathrm{GS}}$ | Gate to Source Voltage | $\pm 30$ | V |
| $\mathrm{I}_{\mathrm{D}}$ | Drain Current -Continuous $\mathrm{T}_{\mathrm{C}}=25^{\circ} \mathrm{C}$ | -3 | A |
|  | -Continuous $\quad \mathrm{T}_{\mathrm{C}}=100^{\circ} \mathrm{C}$ | -1.8 |  |
|  | -Pulsed | -12 |  |
| $\mathrm{P}_{\mathrm{D}}$ | Power Dissipation (Steady State) $\mathrm{T}_{\mathrm{C}}=25^{\circ} \mathrm{C}$ | 42 | W |
| $\mathrm{E}_{\text {AS }}$ | Single Pulse Avalanche Energy (Note 5) | 3.3 | mJ |
| $\mathrm{T}_{\mathrm{J}}, \mathrm{T}_{\text {STG }}$ | Operating and Storage Junction Temperature Range | -55 to +150 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\mathrm{L}}$ | Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds | 300 | ${ }^{\circ} \mathrm{C}$ |
| dv/dt | Peak Diode Recovery dv/dt (Note 2) | -5 | V/ns |

## Thermal Characteristics

| $\mathrm{R}_{\theta \mathrm{JC}}$ | Thermal Resistance, Junction to Case | (Note 1) | 3.0 |  |
| :--- | :--- | :--- | :--- | :--- |
| $\mathrm{R}_{\theta \mathrm{JA}}$ | Thermal Resistance, Junction to Ambient | (Note 1a) | 60 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |

## Package Marking and Ordering Information

| Device Marking | Device | Package | Reel Size | Tape Width | Quantity |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $2523 P$ | FDMC2523P | MLP $3.3 \times 3.3$ | $13 "$ | 12 mm | 3000 units |

Electrical Characteristics $\mathrm{T}_{\mathrm{J}}=25^{\circ} \mathrm{C}$ unless otherwise noted

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Off Characteristics |  |  |  |  |  |  |
| BV ${ }_{\text {DSS }}$ | Drain to Source Breakdown Voltage | $\mathrm{I}_{\mathrm{D}}=-250 \mu \mathrm{~A}, \mathrm{~V}_{\mathrm{GS}}=0 \mathrm{~V}$ | -150 |  |  | V |
| $\frac{\Delta \mathrm{BV}_{\mathrm{DSS}}}{\Delta \mathrm{~T}_{\mathrm{J}}}$ | Breakdown Voltage Temperature Coefficient | $\mathrm{I}_{\mathrm{D}}=-250 \mu \mathrm{~A}$, referenced to $25^{\circ} \mathrm{C}$ |  | -138 |  | $\mathrm{mV} /{ }^{\circ} \mathrm{C}$ |
| ldss | Zero Gate Voltage Drain Current | $\begin{aligned} V_{D S}=-150 V, & V_{G S}=0 V \\ & T_{J}=125^{\circ} C \end{aligned}$ |  |  | -1 -10 | $\mu \mathrm{A}$ |
| IGSs | Gate to Source Leakage Current | $\mathrm{V}_{\mathrm{GS}}= \pm 30 \mathrm{~V}, \mathrm{~V}_{\mathrm{DS}}=0 \mathrm{~V}$ |  |  | $\pm 100$ | nA |

On Characteristics

| $\mathrm{V}_{\mathrm{GS}(\mathrm{th})}$ | Gate to Source Threshold Voltage | $\mathrm{V}_{\mathrm{GS}}=\mathrm{V}_{\mathrm{DS}}, \mathrm{I}_{\mathrm{D}}=-250 \mu \mathrm{~A}$ | -3 | -3.8 | -5 | V |
| :--- | :--- | :--- | :---: | :---: | :---: | :---: |
| $\frac{\Delta \mathrm{~V}_{\mathrm{GS}}(\text { th })}{}$ | Gate to Source Threshold Voltage <br> Temperature Coefficient | $\mathrm{I}_{\mathrm{D}}=-250 \mu \mathrm{~A}$, referenced to $25^{\circ} \mathrm{C}$ |  | 6 |  | $\mathrm{mV} /{ }^{\circ} \mathrm{C}$ |
| $\mathrm{r}_{\mathrm{DS}}$ (on) | Static Drain to Source On Resistance | $\mathrm{V}_{\mathrm{GS}}=-10 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=-1.5 \mathrm{~A}$ |  | 1.1 | 1.5 | $\Omega$ |
|  | $\mathrm{~V}_{\mathrm{GS}}=-10 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=-1.5 \mathrm{~A}, \mathrm{~T}_{\mathrm{J}}=125^{\circ} \mathrm{C}$ |  | 2.0 | 3.6 |  |  |
| $\mathrm{~g}_{\mathrm{FS}}$ | Forward Transconductance | $\mathrm{V}_{\mathrm{DS}}=-40 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=-1.5 \mathrm{~A} \quad$ (Note 4) |  | 1.4 |  | S |

## Dynamic Characteristics

| $\mathrm{C}_{\text {iss }}$ | Input Capacitance | $\mathrm{V}_{\mathrm{DS}}=-25 \mathrm{~V}, \mathrm{~V}_{\mathrm{GS}}=0 \mathrm{~V}$ |  | 200 | 270 | pF |
| :--- | :--- | :--- | :--- | :---: | :---: | :---: |
| $\mathrm{C}_{\text {oss }}$ | Output Capacitance |  |  | 60 | 80 | pF |
| $\mathrm{C}_{\text {rss }}$ | Reverse Transfer Capacitance | $\mathrm{f}=1 \mathrm{MHz}$ |  | 10 | 15 | pF |
| $\mathrm{R}_{\mathrm{g}}$ | Gate Resistance |  | 0.1 | 7.5 | 15 | $\Omega$ |

## Switching Characteristics

| $\mathrm{t}_{\mathrm{d} \text { (on) }}$ | Turn-On Delay Time | $\begin{aligned} & V_{D D}=-75 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=-3 \mathrm{~A} \\ & \mathrm{~V}_{\mathrm{GS}}=-10 \mathrm{~V}, \mathrm{R}_{\mathrm{GEN}}=25 \Omega \end{aligned}$ <br> (Note 3, | 15 | 27 | ns |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{t}_{\mathrm{r}}$ | Rise Time |  | 11 | 20 | ns |
| $\mathrm{t}_{\mathrm{d} \text { (off) }}$ | Turn-Off Delay Time |  | 19 | 35 | ns |
| $\mathrm{t}_{\mathrm{f}}$ | Fall Time |  | 13 | 24 | ns |
| $\mathrm{Q}_{\mathrm{g}}$ | Total Gate Charge | $\begin{aligned} & V_{G S}=-10 V \\ & V_{D D}=-75 \mathrm{~V} \\ & I_{D}=-3 A \end{aligned}$ <br> (Note 3,4) | 6.2 | 9 | nC |
| $\mathrm{Q}_{\mathrm{gs}}$ | Gate to Source Gate Charge |  | 1.4 |  | nC |
| $\mathrm{Q}_{\text {gd }}$ | Gate to Drain "Miller" Charge |  | 3.3 |  | nC |

## Drain-Source Diode Characteristics

| $\mathrm{I}_{\mathrm{S}}$ | Maximum continuous Drain - Source Diode Forward Current |  |  | -3 | A |
| :--- | :--- | :--- | :--- | :---: | :---: |
| $\mathrm{I}_{\mathrm{SM}}$ | Maximum Pulse Drain - Source Doide Forward Current |  |  | -12 | A |
| $\mathrm{~V}_{\mathrm{SD}}$ | Source to Drain Diode Forward Voltage | $\mathrm{V}_{\mathrm{GS}}=0 \mathrm{~V}, \mathrm{I}_{\mathrm{S}}=-3.0 \mathrm{~A}$ |  | -1.8 | -5 |
| $\mathrm{t}_{\mathrm{rr}}$ | Reverse Recovery Time | $\mathrm{I}_{\mathrm{F}}=-3.0 \mathrm{~A}$, di/dt $=100 \mathrm{~A} / \mu \mathrm{S} \quad$ (Note 3) |  | V |  |
| $\mathrm{Q}_{\mathrm{rr}}$ | Reverse Recovery Charge |  | 03 |  | ns |

## Notes:

1: $R_{\theta J A}$ is the sum of the junction-to-case and case-to- ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta J C}$ is guaranteed by design while $R_{\theta C A}$ is determined by the user's board design.


2: $\mathrm{I}_{\mathrm{SD}} \leq-3 \mathrm{~A}, \mathrm{dl} / \mathrm{dt} \leq 300 \mathrm{~A} / \mathrm{us}, \mathrm{V}_{\mathrm{DD}} \leq \mathrm{B}_{\mathrm{VDSS}}$, Starting $\mathrm{T}_{\mathrm{J}}=25^{\circ} \mathrm{C}$
3: Pulse Test: Pulse Width $<300 \mu \mathrm{~s}$, Duty cycle $<2.0 \%$
4: Essentially independent of operating temperature.
5: $E_{A S}$ of 3.3 mJ is based on starting $T_{J}=25^{\circ} \mathrm{C}$; P-ch: $L=3 \mathrm{mH}, \mathrm{I}_{\mathrm{AS}}=-1.5 \mathrm{~A}, \mathrm{~V}_{\mathrm{DD}}=-150 \mathrm{~V}, \mathrm{~V}_{\mathrm{GS}}=-10 \mathrm{~V}$.

Typical Characteristics $\mathrm{T}_{J}=25^{\circ} \mathrm{C}$ unless otherwise noted


Figure 1. On-Region Characteristics


Figure 3. Normalized On-Resistance vs Junction Temperature


Figure 5. Transfer Characteristics


Figure2. Normalized On-Resistance vs Drain Current and Gate Voltage


Figure 4. On-Resistance vs Gate to Source Voltage


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $\mathrm{T}_{\mathrm{J}}=25^{\circ} \mathrm{C}$ unless otherwise noted


Figure 7. Gate Charge Characteristics


Figure9. Unclamped Inductive Switching Capability


Figure8. Capacitancevs Drain to Source Voltage


Figure 10. Forward Bias Safe Operating Area


Figure 11. Single Pulse Maximum Power Dissipation

Typical Characteristics $\mathrm{T}_{J}=25^{\circ} \mathrm{C}$ unless otherwise noted


Figure 12. Transient Thermal Response Curve



RECOMMENDED LAND PATTERN

## NOTES:

A. DOES NOT CONFORM TO JEDEC REGISTRATION MO-229
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
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#### Abstract

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